Emune & Tynestens

BTL / BL

GTAz GTz GDAz



MEK BTL/BL Dual side In-line AOI systems

Featuring industry leading GTAz head and optional high Dual side or bottom up only inline full featured inspection clearance GDAz head The latest generation of high speed, high quality cameras High Speed 90Fps thunderbolt main camera and USB 3 Vision No capture card requirements. Cameras side cameras Top and bottom heads are linked to allow parallel inspection Synchronized top and bottom inspection Reliable solder joint meniscus and pad surface analysis (to find Multi-color 4 angle lighting with Line Source Coaxial Lighting and meniscus and paste printing defects) Meniscus Profiler use inspection in all stages of the production process Inspects:.... Components: SMT & THT (missing, type, polarity, offset, text, colors, etc.) Component Height and Coplanarity Solder Paste and CIP (Components in Paste; pre-reflow) Soldering: Post Reflow, Post Wave, Selective, Manual THT solder inspection Integrate AOI efficiently in your existing operations and factory Flexible classification and reporting scenarios..... lav-out Inspect solder joints without shadow effects from tall Line Sourced DOAL(Direct On Axis Lighting) coaxial lighting components nearby and accurate inspection model building system with high resolution Telecentric Optics..... Find defects easier including printing defects on Gold or Cu Low Noise Large CCD High Speed 24 bit Color Camera plated PCB's Powerful algorithms to achieve an optimal balance between Synthetic Imaging and Spectral Analysis..... defect detection and false reject levels in shortest time Use for automatic inspection, classification and repair Triple use of side camera's Program in minutes to verify your production line is set-up Prototype mode for 1st off inspection..... correctly before starting full production Compensate for PCB warp and adapt to tall component and In height adjustable optical head



sandwich assemblies



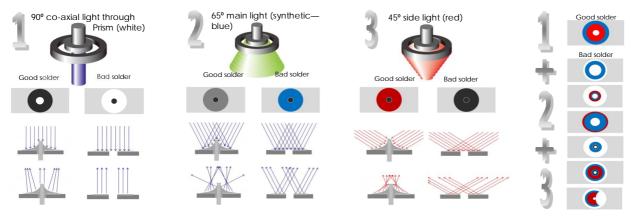
Hardware and Software Features

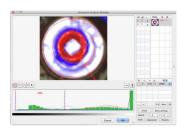
Sixteen possible head combinations

18 Cameras, 9 Top and 9 Bottom Cameras to 2 Camera Single top and Bottom Cameras. The D22X BTL is the ultimate in platform flexibility

THT Solder Inspection

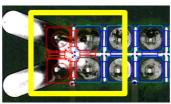
Scalable inspection points for the wide variety of Solder land shapes and pin sizes, Bridge and solder ball detection algorithms.



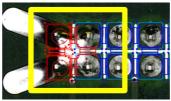


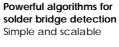
Histogram Analysis algorithms

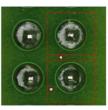
Condition based decision. Tolerances can be set tightly Close to zero false alarms



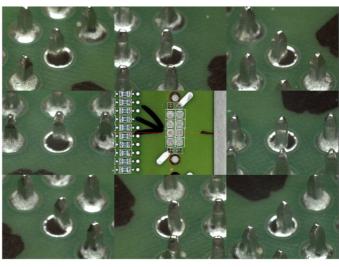
Dedicated algorithms for solder balls detection













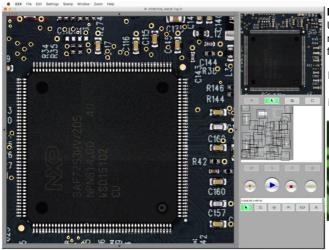


8x Angular Side Sensors (Only available for GTAz and GDAz models) Simultaneously operating, multiplexed side view sensors with CameraLink interface — 45/45 arrangement — Triple use: Active automatic inspection, classification and repair — clear 9 angles defect review — high magnification 50x (10µm/pixel) — Full Color — Auto highlight — Large sensor pixels — 9 view images also in backup database





Hardware and Software Features — Continued

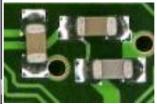


Double size FOV (Field of view)

Up to 2x faster inspection over previous generations of machines. Square FOV combined with circular lighting allows for program rotation without time consuming debugging.

Large pixel image capturing sensor

18.8µm² pixel size — less noise — smooth and detailed image— great dynamic range





High dynamics sensor

Conventional sensor

Height Adjustable Optical Head

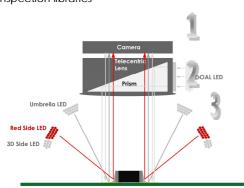
Z-Axis moving Top Camera, Light and Side View cameras — Adaption to any PCB Thickness — PCB Warp Compensation — Inspection of PCB's with very tall components — Reliable text and/or polarity inspection on tall components Inspection of "Sandwich" assemblies without need of jigs and multiple inspections

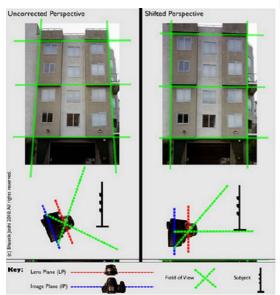
Omnidirectional multi angle, multi color LED lighting

Optimal light no matter component direction — 3D color profile of solder meniscus — Reliable defect decision by the software — Decide Good Solder, No Solder, Lack of Solder and Too much solder for SMT and THT solder joints

SMT Solder Inspection

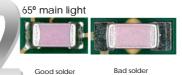
Full solder profiling and histogram algorithm analysis. Simple prebuilt solder inspection libraries







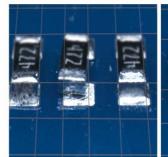


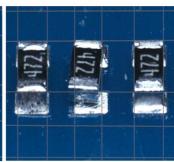




Shift & Tilt Side View lenses

Distortion free side images across whole FoV. Every point on the PCB within the FoV has same distance to the capturing sensor despite the angle of the optics





Without Shift&Tilt

Shift&Tilt



Inline BTL



Bottom & Top Simultaneous inspection

GTAz + GDAz

In-Line Series Specifications	PowerSpector GTAz + GDAz 350BTL	PowerSpector GTAz + GDAz 550BTL
Maximum PCB Size	350x250mm (13.8"x9.8")	550x550mm (21.6"x21.6")
Characteristics		
Product type	Automatic Optical Inspector	
In-line/Off-line	In-Line	
Camera movement	X + Y Direction	
PCB movement	Stationary during inspection	
Parts inspection	Presence, Polarity, Offset, Correctness, Soldering, Height	
Printing/paste inspection	Offset, Smearing, Bridges, Uniformity	
mage Processing	Synthetic Imaging, Spectral Analysis, Greyscale limits	
mage Parameters	Brightness, Hue, Saturation via Filters	
Camera type	Digital color Thunderbolt interface 90 Fps	
Camera Field Of View/Resolution	38.5x38.5mm/18.75μm or 19.5x19.5mm/10μm	
.ens	Telecentric lens with built in prism for DOAL Lighting	
Lighting system	Omnidirectional T Quad LED rings: Side White, Side Red, Main, Line Sourced DOAL (Diffused On Axis Lighting (Coaxial))	
Specifications		
Smallest inspection component size	01005" (0.4x0.2mm) (10μm resolution)	
Positioning accuracy	Pixel related Feedback Loop	
Component clearance (top)	GTAz 30mm (1.2") GDAz 60 mm (2.4")	
Side Cameras	8x Digital color USB 3.0 Vision in 45/45 orientation	
Z-Axis movement range	30mm (1.2")	
Component clearance (bottom)	30mm (1.2") with GTAz bottom camera or 60mm (2.4") GDAz bottom camera	
Maximum PCB Size	350x250mm (13.8" x 9.8")	550x550mm (21.6" x 21.6")
Novement speed	720mm/s	
nspection capacity typical	2750ppm	
Electrical requirements	100-240 VAC / 330W	
Conveyor		
Conveyor belt speed	10-500mm/s (0	4-19.7"/s)
Conveyor configuration	Left>Right, Front rail fixed, Height 830-950mm	
PCB Clamping	Top Justified, Ruler Blade, Top & Edge Clamping, Sensor Stopper	
Minimum board size	50x50mm (2.0" x 2.0")	
Board thickness	0.6-4mm (24mils - 79mils)	
Interfacing		
Control PC type	Apple Mac Mini or iMac x2	
Control interface	SMEMA (conveyer)	
Data interface	USB and Thunderbolt	
Programming Interface	CSV Centroid file (Placement file)	
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windows 7/8/10) (option)	
Brd party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)	
General		
Operating temperature	15-30 deg. C(60-90 deg. F)	
Operating humidity	15-80 % RH	
	W878 x D916 x H1313 W1078 x D1320 x H1317	
External size	(34.6" x 36.1" x 51.7")	(42.4" x 52" x 51.8")
Weight	240kg (397lbs)	400kg (529lbs)

 $\label{eq:mean_problem} \textit{Mek Europe reserves the right to change the design and specifications without notice.} \\ \textit{@} \textit{Mek Europe BV, 2019}$

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Inline BTL



Bottom & Top Simultaneous inspection

GTz + GTz

In-Line Series Specifications	PowerSpector GTz + GTz 350BTL	PowerSpector GTz + GTz 550BTL
Maximum PCB Size	350x250mm (13.8"x9.8")	550x550mm (21.6"x21.6")
Characteristics	330823011111 (13.0 87.0)	330,03011111 (21.0 ,21.0)
Product type	Automatic Optical Inspector	
n-line/Off-line	In-Line	
Camera movement	X + Y Direction	
PCB movement	Stationary during inspection	
Parts inspection	Presence, Polarity, Offset, Correctness, Soldering, Height	
Printing/paste inspection	Offset, Smearing, Bridges, Uniformity	
mage Processing	Synthetic Imaging, Spectral Analysis, Greyscale limits	
mage Parameters	Brightness, Hue, Saturation via Filters	
Camera type	Digital color Thunderbolt interface 90 Fps	
Camera Field Of View/Resolution	38.5x38.5mm/18.75µm or 19.5x19.5mm/10µm	
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ighting system	Omnidirectional T Quad LED rings: Side Whit (Diffused On Axis Ligh	e, Side Red, Main, Line Sourced DOAI
Specifications		
Smallest inspection component size	01005" (0.4x0.2mm)(10µm resolution)	
Positioning accuracy	Pixel related Feedback Loop	
Component clearance (top)	GTz 40mm (1.5") extendable to 60mm	
Side Cameras	NA	
Z-Axis movement range	30mm (1.2")	
Component clearance (bottom)	30mm (1.2")	
Maximum PCB Size	350x250mm (13.8" x 9.8")	550x550mm (21.6" x 21.6")
Novement speed	720mm.	
nspection capacity typical	2750ppm	
Electrical requirements	100-240 VAC / 330W	
Conveyor		, , , , , , , , , , , , , , , , , , , ,
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Conveyor configuration	Left>Right, Front rail fixed, Height 830-950mm	
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Minimum board size	50x50mm (2.0" x 2.0")	
Board thickness	0.6-4mm (24mils - 79mils)	
Interfacing		
Control PC type	Apple Mac Mini or iMac x2	
Control interface	SMEMA (conveyer)	
Data interface	USB and Thunderbolt	
Programming Interface	CSV Centroid file (Placement file)	
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windo	ows 7/8/10) (option)
3rd party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)	
General		
Operating temperature	15-30 deg. C(60-90 deg. F)	
Operating humidity	15-80 % RH	
Futam at aire	W878 x D916 x H1313	W1078 x D1320 x H1317
External size	(34.6" x 36.1" x 51.7") 240kg (397lbs)	(42.4" x 52" x 51.8")

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